

DA2JF23

Silicon epitaxial planar type

For small current rectification

■ Features

- Small reverse current I_R
- Contributes to miniaturization of sets, reduction of component count.
- Eco-friendly Halogen-free package

■ Packaging

Embossed type (Thermo-compression sealing): 3000 pcs / reel (standard)

■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

Parameter	Symbol	Rating	Unit
Repetitive peak reverse voltage	V_{RRM}	300	V
Non-repetitive peak reverse surge voltage	V_{RSM}	300	V
Forward current (Average) *1	$I_{F(AV)}$	0.3	A
Non-repetitive peak forward surge current *2	I_{FSM}	3.0	A
Junction temperature	T_j	-40 to +150	$^\circ\text{C}$
Storage temperature	T_{stg}	-40 to +150	$^\circ\text{C}$

Note) *1: $T_a = 90^\circ\text{C}$, with DC wave

*2: 50 Hz sine wave 1 cycle (Non-repetitive peak current)

■ Package

- Code
SMini2-F5-B
- Pin Name
1: Cathode
2: Anode

■ Marking Symbol: 4A

■ Electrical Characteristics $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Forward voltage	V_F	$I_F = 300 \text{ mA}$			1.25	V
Reverse current	I_{RRM}	$V_{RRM} = 300 \text{ V}$			1.0	μA
Terminal capacitance	C_t	$V_R = 0 \text{ V}, f = 1 \text{ MHz}$		3.5		pF
Reverse recovery time *2	t_{rr}	$I_F = 100 \text{ mA}, I_R = 200 \text{ mA},$ $I_{Tr} = 0.25 \times I_R$		400		ns
Thermal resistance (j-a) *1	$R_{th(j-a)}$			160		$^\circ\text{C/W}$

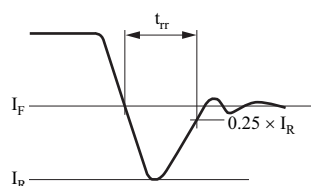
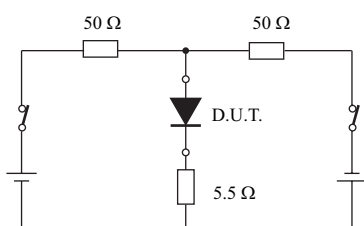
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

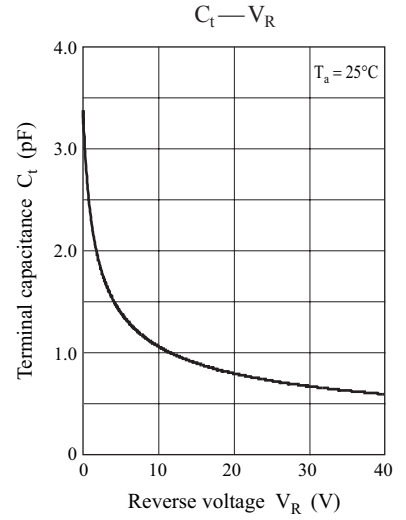
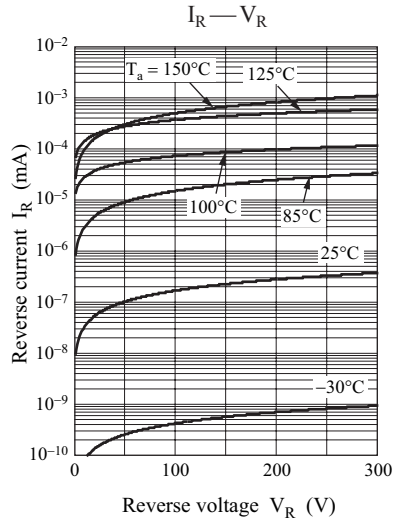
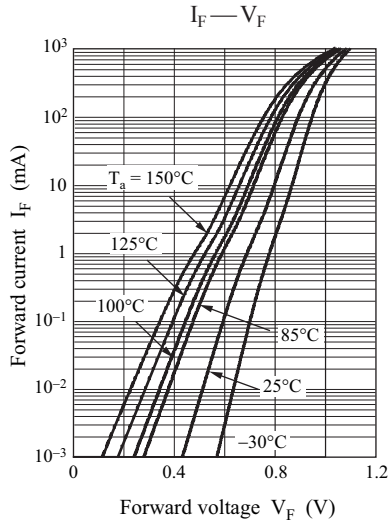
2. This product is sensitive to electric shock (static electricity, etc.). Due attention must be paid on the charge of a human body and the leakage of current from the operating equipment.

3. Absolute frequency of input and output is 20 MHz

4. *1: Mounted on an alumina PC board (Board: 20 mm × 50 mm, Soldering land: 2 mm × 2 mm)

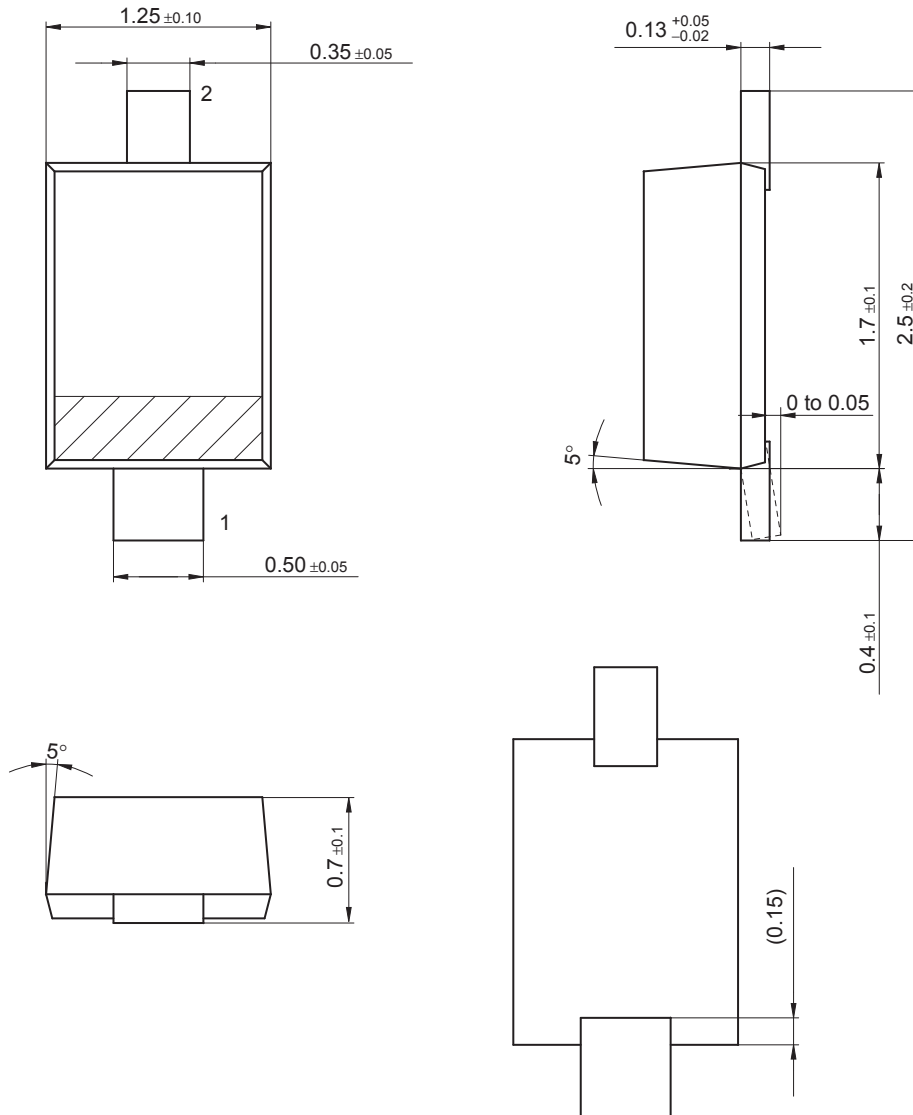
*2: t_{rr} measurement circuit





SMini2-F5-B

Unit: mm



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